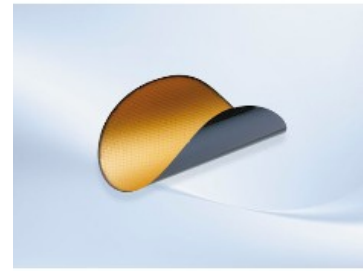


MOSFET

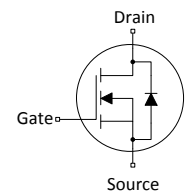
OptiMOS™3 Power MOS Transistor Chip

- N-channel enhancement mode
- For dynamic characterization refer to the datasheet of IPB011N04N G
- AQL 0.65 for visual inspection according to failure catalogue
- Electrostatic Discharge Sensitive Device according to MIL-STD 883C
- Die bond: soldered or glued
- Backside metallization: NiV system
- Frontside metallization: AlCu system
- Passivation: Nitride + Imide

Power MOS Transistor Chip


Table 1 Key Performance Parameters

Parameter	Value	Unit
$V_{(BR)DSS}$	40	V
$R_{DS(on)}$	1.1 ¹⁾	mΩ
Die size	5.9 x 3.7	mm ²
Thickness	175	μm



Type / Ordering Code	Package	Marking	Related Links
IPC218N04N3	Chip	not defined	-

1 Electrical Characteristics on Wafer Level

at $T_j = 25^\circ\text{C}$, unless otherwise specified

Table 2

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	40	-	-	V	$V_{GS}=0\text{ V}$, $I_D=1\text{ mA}$
Gate threshold voltage	$V_{GS(th)}$	2	-	4	V	$V_{DS}=V_{GS}$, $I_D=200\text{ μA}$
Zero gate voltage drain current	I_{DSS}	-	0.1	2	μA	$V_{GS}=0\text{ V}$, $V_{DS}=40\text{ V}$
Gate-source leakage current	I_{GSS}	-	2	200	nA	$V_{GS}=20\text{ V}$, $V_{DS}=0\text{ V}$
Drain-source on- resistance	$R_{DS(on)}$	-	0.9 ²⁾	50 ³⁾	mΩ	$V_{GS}=10\text{ V}$, $I_D=2.0\text{ A}$
Reverse diode forward on-voltage	V_{SD}	-	0.86	1.1	V	$V_{GS}=0\text{ V}$, $I_F=1\text{ A}$
Internal gate resistance	R_G	-	1.5	-	Ω	-
Avalanche energy, single pulse	E_{AS}	-	-	525 ⁴⁾	mJ	$I_D=50\text{ A}$, $R_{GS}=25\text{ Ω}$

¹⁾ packaged in a PG-TO263-7 (see ref. product)

²⁾ typical bare die $R_{DS(on)}$; $V_{GS}=10\text{ V}$ when used with 4*500μm Al-wedge double-stitch bonding

³⁾ limited by wafer test-equipment

⁴⁾ Wafer tested. For general avalanche capability refer to the datasheet of IPB011N04N G

2 Package Outlines

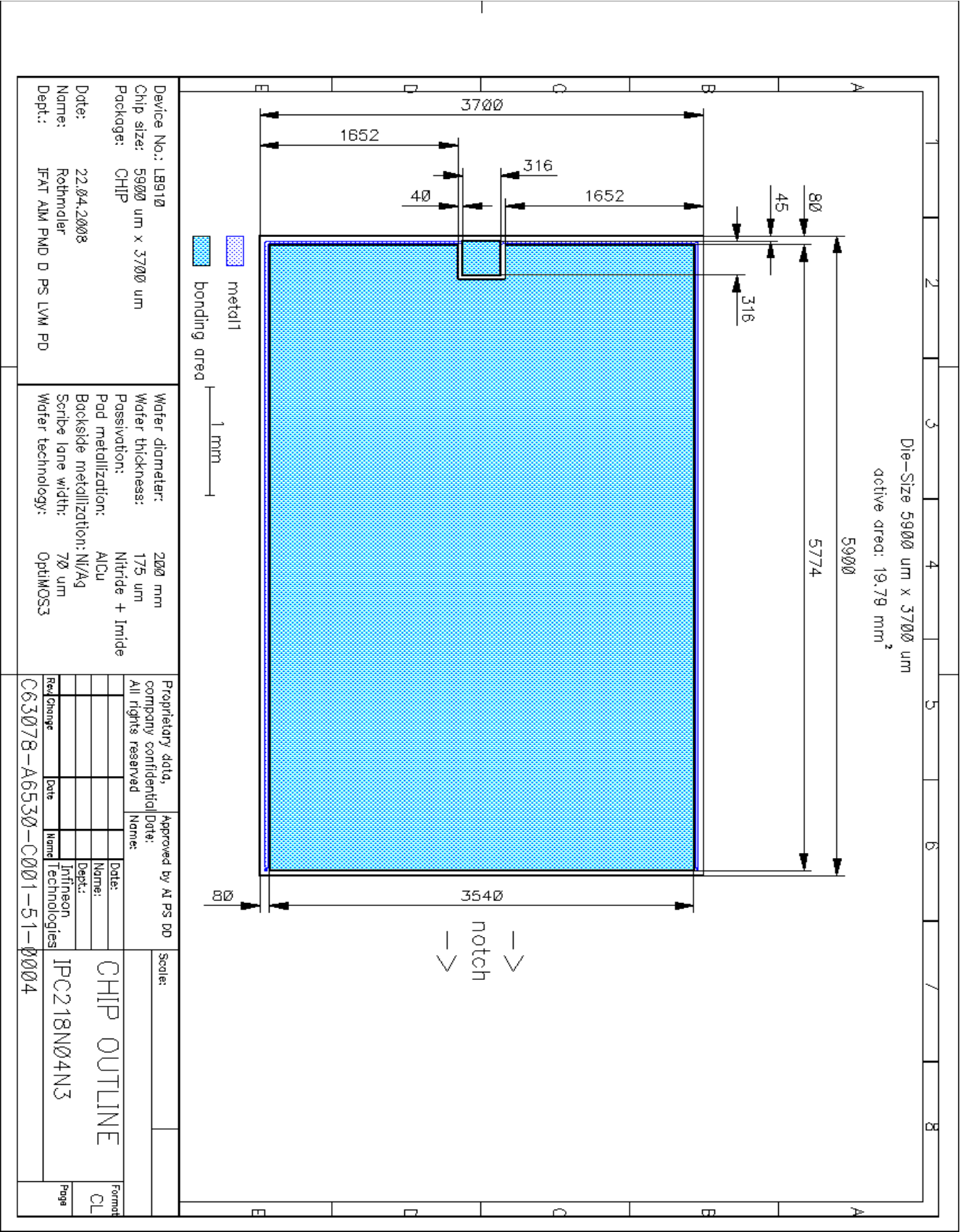


Figure 1 Outline Chip, dimensions in µm

Revision History

IPC218N04N3

Revision: 2017-07-17, Rev. 2.6

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.5	2014-07-25	Release Final Version
2.6	2017-07-17	Change typical RDS(on)

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